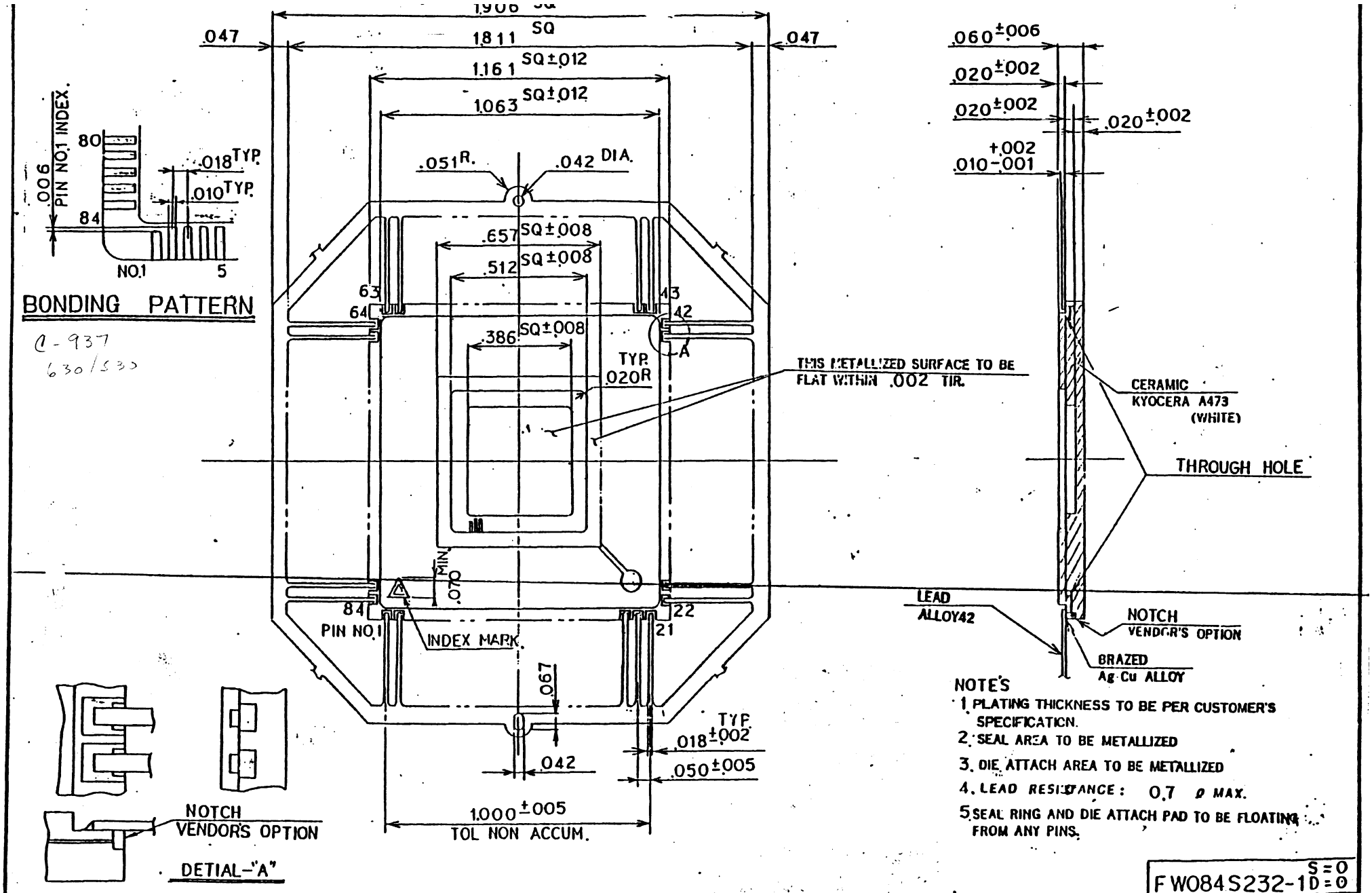

C-937
630/530

NOTE'S

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED
3. DIE ATTACH AREA TO BE METALLIZED
4. LEAD RESISTANCE: 0.7 Ω MAX.
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

F W084 S232-1 S=0 D=0

MODIFICATIONS / CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME		TOLERANCES UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED
84	LEAD FLAT PACKAGE		K. Chyoh	[illegible]
SCALE	MATERIAL	±1.0% N.L.T.±.005	APPROVED	DATE
3 : 1	AS INDICATED			MAR.4,'86

SSM P/N CCF08403